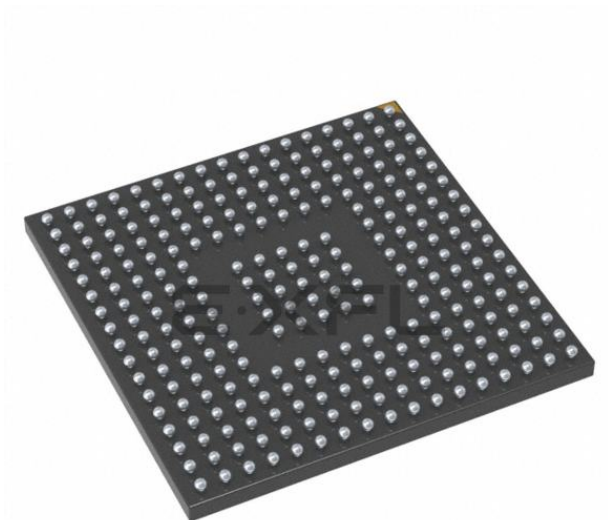




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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex® -M7
Core Size	32-Bit Single-Core
Speed	216MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I ² C, IrDA, LINbus, MMC/SD/SDIO, QSPI, SAI, SPDIF, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I ² S, LCD, POR, PWM, WDT
Number of I/O	140
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512K x 8
Voltage - Supply (Vcc/Vdd)	1.7V ~ 3.6V
Data Converters	A/D 24x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	201-UF BGA
Supplier Device Package	176+25UF BGA (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/stm32f767igk6

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The devices embed two dedicated PLL (PLLI2S and PLLSAI) which allow to achieve audio class performance. In this case, the I²S and SAI master clock can generate all standard sampling frequencies from 8 kHz to 192 kHz.

2.16 Boot modes

At startup, the boot memory space is selected by the BOOT pin and BOOT_ADDx option bytes, allowing to program any boot memory address from 0x0000 0000 to 0x3FFF FFFF which includes:

- All Flash address space mapped on ITCM or AXIM interface
- All RAM address space: ITCM, DTCM RAMs and SRAMs mapped on AXIM interface
- The System memory bootloader

The boot loader is located in system memory. It is used to reprogram the Flash memory through a serial interface. Refer to *STM32 microcontroller system memory boot mode* application note (AN2606) for details.

2.17 Power supply schemes

- $V_{DD} = 1.7$ to 3.6 V: external power supply for I/Os and the internal regulator (when enabled), provided externally through V_{DD} pins.
- V_{SSA} , $V_{DDA} = 1.7$ to 3.6 V: external analog power supplies for ADC, DAC, Reset blocks, RCs and PLL. V_{DDA} and V_{SSA} must be connected to V_{DD} and V_{SS} , respectively.
- $V_{BAT} = 1.65$ to 3.6 V: power supply for RTC, external clock 32 kHz oscillator and backup registers (through power switch) when V_{DD} is not present.

Note: V_{DD}/V_{DDA} minimum value of 1.7 V is obtained when the internal reset is OFF (refer to [Section 2.18.2: Internal reset OFF](#)). Refer to [Table 3: Voltage regulator configuration mode versus device operating mode](#) to identify the packages supporting this option.

- $V_{DDSDMMC}$ can be connected either to V_{DD} or an external independent power supply (1.8 to 3.6V) for SDMMC2 pins (clock, command, and 4-bit data). For example, when the device is powered at 1.8V, an independent power supply 2.7V can be connected to $V_{DDSDMMC}$. When the $V_{DDSDMMC}$ is connected to a separated power supply, it is independent from V_{DD} or V_{DDA} but it must be the last supply to be provided and the first to disappear. The following conditions $V_{DDSDMMC}$ must be respected:
 - During the power-on phase ($V_{DD} < V_{DD_MIN}$), $V_{DDSDMMC}$ should be always lower than V_{DD}
 - During the power-down phase ($V_{DD} < V_{DD_MIN}$), $V_{DDSDMMC}$ should be always lower than V_{DD}
 - The $V_{DDSDMMC}$ rising and falling time rate specifications must be respected (see [Table 20](#) and [Table 21](#))
 - In operating mode phase, $V_{DDSDMMC}$ could be lower or higher than V_{DD} : All associated GPIOs powered by $V_{DDSDMMC}$ are operating between $V_{DDSDMMC_MIN}$ and $V_{DDSDMMC_MAX}$.
- V_{DDUSB} can be connected either to V_{DD} or an external independent power supply (3.0 to 3.6V) for USB transceivers (refer to [Figure 4](#) and [Figure 5](#)). For example, when the device is powered at 1.8V, an independent power supply 3.3V can be connected to V_{DDUSB} . When the V_{DDUSB} is connected to a separated power supply, it is independent from V_{DD} or V_{DDA} but it must be the last supply to be provided and the first to

Table 6. Timer feature comparison

Timer type	Timer	Counter resolution	Counter type	Prescaler factor	DMA request generation	Capture/compare channels	Complementary output	Max interface clock (MHz)	Max timer clock (MHz) ⁽¹⁾
Advanced -control	TIM1, TIM8	16-bit	Up, Down, Up/down	Any integer between 1 and 65536	Yes	4	Yes	108	216
General purpose	TIM2, TIM5	32-bit	Up, Down, Up/down	Any integer between 1 and 65536	Yes	4	No	54	108/216
	TIM3, TIM4	16-bit	Up, Down, Up/down	Any integer between 1 and 65536	Yes	4	No	54	108/216
	TIM9	16-bit	Up	Any integer between 1 and 65536	No	2	No	108	216
	TIM10, TIM11	16-bit	Up	Any integer between 1 and 65536	No	1	No	108	216
	TIM12	16-bit	Up	Any integer between 1 and 65536	No	2	No	54	108/216
	TIM13, TIM14	16-bit	Up	Any integer between 1 and 65536	No	1	No	54	108/216
Basic	TIM6, TIM7	16-bit	Up	Any integer between 1 and 65536	Yes	0	No	54	108/216

1. The maximum timer clock is either 108 or 216 MHz depending on TIMPRE bit configuration in the RCC_DCKCFGR register.

2.25 Universal synchronous/asynchronous receiver transmitters (USART)

The devices embed USART. Refer to [Table 8: USART implementation](#) for the features implementation.

The universal synchronous asynchronous receiver transmitter (USART) offers a flexible means of full-duplex data exchange with external equipment requiring an industry standard NRZ asynchronous serial data format.

The USART peripheral supports:

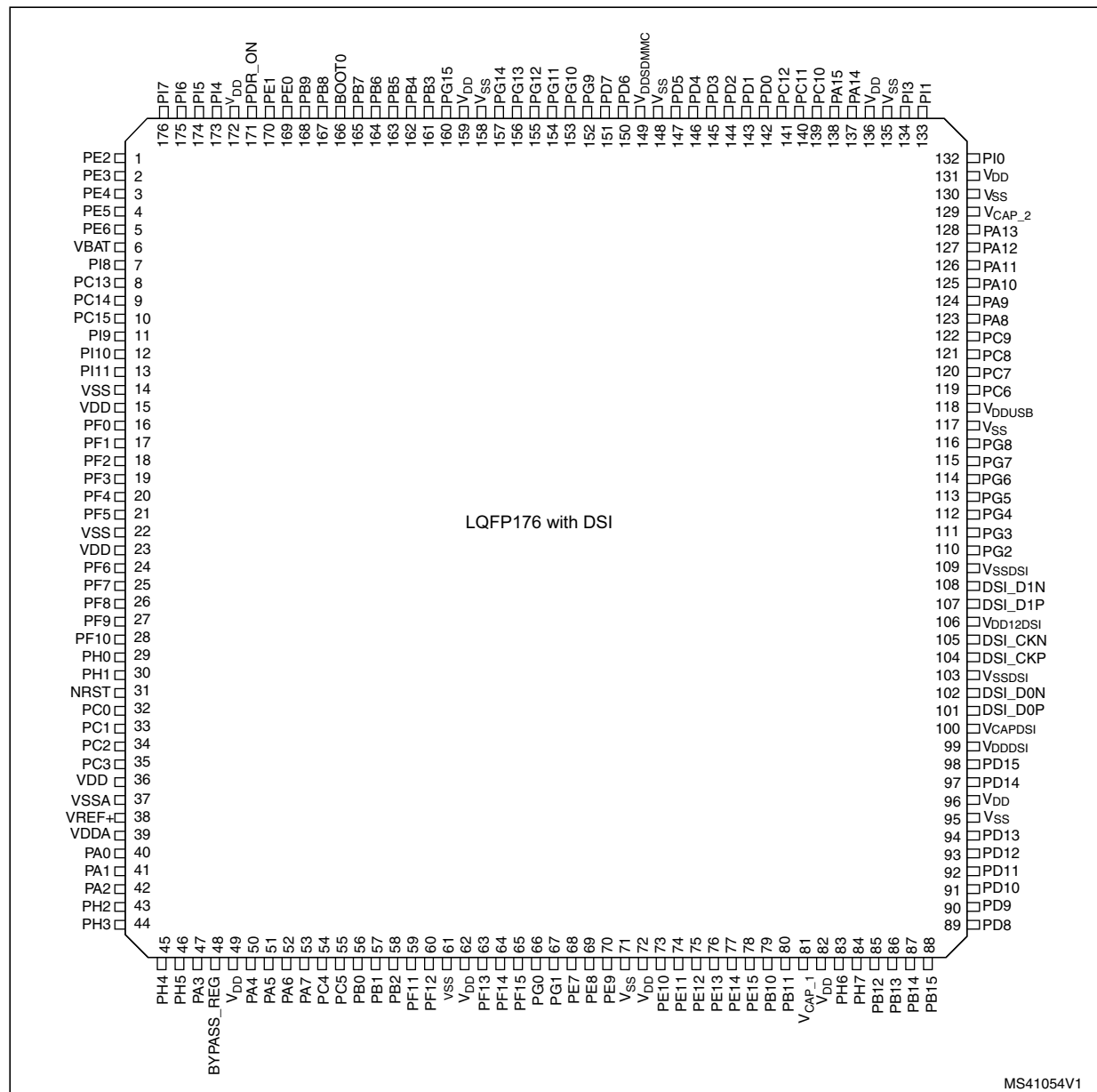
- Full-duplex asynchronous communications
- Configurable oversampling method by 16 or 8 to give flexibility between speed and clock tolerance
- Dual clock domain allowing convenient baud rate programming independent from the PCLK reprogramming
- A common programmable transmit and receive baud rate of up to 27 Mbit/s when the USART clock source is system clock frequency (max is 216 MHz) and oversampling by 8 is used.
- Auto baud rate detection
- Programmable data word length (7 or 8 or 9 bits) word length
- Programmable data order with MSB-first or LSB-first shifting
- Programmable parity (odd, even, no parity)
- Configurable stop bits (1 or 1.5 or 2 stop bits)
- Synchronous mode and clock output for synchronous communications
- Single-wire half-duplex communications
- Separate signal polarity control for transmission and reception
- Swappable Tx/Rx pin configuration
- Hardware flow control for modem and RS-485 transceiver
- Multiprocessor communications
- LIN master synchronous break send capability and LIN slave break detection capability
- IrDA SIR encoder decoder supporting 3/16 bit duration for normal mode
- Smartcard mode (T=0 and T=1 asynchronous protocols for Smartcards as defined in the ISO/IEC 7816-3 standard)
- Support for Modbus communication

[Table 8](#) summarizes the implementation of all U(S)ARTs instances

Table 8. USART implementation

features ⁽¹⁾	USART1/2/3/6	UART4/5/7/8
Data Length	7, 8 and 9 bits	
Hardware flow control for modem	X	X
Continuous communication using DMA	X	X
Multiprocessor communication	X	X
Synchronous mode	X	-

Figure 14. STM32F769xx LQFP176 pinout



1. The above figure shows the package top view.

Table 10. STM32F765xx, STM32F767xx, STM32F768Ax and STM32F769xx pin and ball definitions (continued)

Pin Number										Pin name (function after reset)	Pin type	I/O structure	Notes	Alternate functions	Additional functions
STM32F765xx STM32F767xx						STM32F768Ax STM32F769xx									
LQFP100	LQFP144	UFBGA176	LQFP176	LQFP208	TFBGA216	WLCSP180 ⁽¹⁾	LQFP176	LQFP208	TFBGA216						
-	19	K1	25	28	K1	NC	25	28	K1	PF7	I/O	FT	-	TIM11_CH1, SPI5_SCK, SAI1_MCLK_B, UART7_TX, QUADSPI_BK1_IO2, EVENTOUT	ADC3_IN5
-	20	L3	26	29	L3	NC	26	29	L3	PF8	I/O	FT	-	SPI5_MISO, SAI1_SCK_B, UART7_RTS, TIM13_CH1, QUADSPI_BK1_IO0, EVENTOUT	ADC3_IN6
-	21	L2	27	30	L2	NC	27	30	L2	PF9	I/O	FT	-	SPI5_MOSI, SAI1_FS_B, UART7_CTS, TIM14_CH1, QUADSPI_BK1_IO1, EVENTOUT	ADC3_IN7
-	22	L1	28	31	L1	K11	28	31	L1	PF10	I/O	FT	-	QUADSPI_CLK, DCMI_D11, LCD_DE, EVENTOUT	ADC3_IN8
12	23	G1	29	32	G1	K12	29	32	G1	PH0-OSC_IN	I/O	FT	(3)	EVENTOUT	OSC_IN
13	24	H1	30	33	H1	K13	30	33	H1	PH1-OSC_OUT	I/O	FT	(3)	EVENTOUT	OSC_OUT
14	25	J1	31	34	J1	L11	31	34	J1	NRST	I/O	RS T	-	-	-
15	26	M2	32	35	M2	L12	32	35	M2	PC0	I/O	FT	-	DFSDM1_CKIN0, DFSDM1_DATIN4, SAI2_FS_B, OTG_HS_ULPI_STP, FMC_SDNWE, LCD_R5, EVENTOUT	ADC1_IN10, ADC2_IN10, ADC3_IN10
16	27	M3	33	36	M3	L13	33	36	M3	PC1	I/O	FT	-	TRACED0, DFSDM1_DATIN0, SPI2_MOSI/I2S2_SD, SAI1_SD_A, DFSDM1_CKIN4, ETH_MDC, MDIOS_MDC, EVENTOUT	ADC1_IN11, ADC2_IN11, ADC3_IN11, RTC_TAMP 3/WKUP3

Table 10. STM32F765xx, STM32F767xx, STM32F768Ax and STM32F769xx pin and ball definitions (continued)

Pin Number										Pin name (function after reset)	Pin type	I/O structure	Notes	Alternate functions	Additional functions
STM32F765xx STM32F767xx						STM32F768Ax STM32F769xx									
LQFP100	LQFP144	UFBGA176	LQFP176	LQFP208	TFBGA216	WLCSP180 ⁽¹⁾	LQFP176	LQFP208	TFBGA216						
-	51	M8	61	72	K7	P9	61	72	K7	VSS	S	-	-	-	
-	52	N8	62	73	L8	M8	62	73	L8	VDD	S	-	-	-	
-	53	N6	63	74	N6	L8	63	74	N6	PF13	I/O	FT	-	I2C4_SMBA, DFSDM1_DATIN6, FMC_A7, EVENTOUT	-
-	54	R7	64	75	P6	K8	64	75	P6	PF14	I/O	FT	-	I2C4_SCL, DFSDM1_CKIN6, FMC_A8, EVENTOUT	-
-	55	P7	65	76	M8	P8	65	76	M8	PF15	I/O	FT	-	I2C4_SDA, FMC_A9, EVENTOUT	-
-	56	N7	66	77	N7	N8	66	77	N7	PG0	I/O	FT	-	FMC_A10, EVENTOUT	-
-	57	M7	67	78	M7	L7	67	78	M7	PG1	I/O	FT	-	FMC_A11, EVENTOUT	-
37	58	R8	68	79	R8	M7	68	79	R8	PE7	I/O	FT	-	TIM1_ETR, DFSDM1_DATIN2, UART7_RX, QUADSPI_BK2_IO0, FMC_D4, EVENTOUT	-
38	59	P8	69	80	N9	N7	69	80	N9	PE8	I/O	FT	-	TIM1_CH1N, DFSDM1_CKIN2, UART7_TX, QUADSPI_BK2_IO1, FMC_D5, EVENTOUT	-
39	60	P9	70	81	P9	P7	70	81	P9	PE9	I/O	FT	-	TIM1_CH1, DFSDM1_CKOUT, UART7_RTS, QUADSPI_BK2_IO2, FMC_D6, EVENTOUT	-
-	61	M9	71	82	K8	-	71	82	K8	VSS	S	-	-	-	-
-	62	N9	72	83	L9	-	72	83	L9	VDD	S	-	-	-	-

Table 12. STM32F765xx, STM32F767xx, STM32F768Ax and STM32F769xx alternate function mapping (continued)

Port		AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
		SYS	I2C4/UART5/TIM1/2	TIM3/4/5	TIM8/9/10/11/LPTIM1/DFSDM1/CEC	I2C1/2/3/4/USART1/CEC	SPI1/I2S1/SPI2/I2S2/SPI3/I2S3/SAI1/I2C4/UART4/DFSDM1	SPI2/I2S2/SPI3/I2S3/SAI1/I2C4/UART4/DFSDM1	SPI2/I2S2/SPI3/I2S3/SAI1/I2C4/UART4/DFSDM1	SPI6/SAI2/USART6/USART4/5/7/8/OTG_FS/SPDIF	CAN1/2/TIM12/13/14/QUADSPI/FMC/LCD	SAI2/QUADSPI/SDMMC2/DFSM1/OTG2_HS/OTG1_FS/LCD	I2C4/CAN3/SDMMC2/ETH	UART7/FMC/SDMMC1/MDIOS/OTG2_FS	DCMI/LCD/DSI	LCD	SYS
Port F	PF0	-	-	-	-	I2C2_SD_A	-	-	-	-	-	-	-	FMC_A0	-	-	EVEN TOUT
	PF1	-	-	-	-	I2C2_SCL	-	-	-	-	-	-	-	FMC_A1	-	-	EVEN TOUT
	PF2	-	-	-	-	I2C2_SMB_A	-	-	-	-	-	-	-	FMC_A2	-	-	EVEN TOUT
	PF3	-	-	-	-	-	-	-	-	-	-	-	-	FMC_A3	-	-	EVEN TOUT
	PF4	-	-	-	-	-	-	-	-	-	-	-	-	FMC_A4	-	-	EVEN TOUT
	PF5	-	-	-	-	-	-	-	-	-	-	-	-	FMC_A5	-	-	EVEN TOUT
	PF6	-	-	-	TIM10_CH1	-	SPI5_NSS	SAI1_SDB	-	UART7_Rx	QUADSPI_BK1_IO3	-	-	-	-	-	EVEN TOUT
	PF7	-	-	-	TIM11_CH1	-	SPI5_SCK	SAI1_MCLK_B	-	UART7_Tx	QUADSPI_BK1_IO2	-	-	-	-	-	EVEN TOUT
	PF8	-	-	-	-	-	SPI5_MISO	SAI1_SCK_B	-	UART7_RTS	TIM13_CH1	QUADSPI_BK1_IO0	-	-	-	-	EVEN TOUT
	PF9	-	-	-	-	-	SPI5_MOSI	SAI1_FSB	-	UART7_CTS	TIM14_CH1	QUADSPI_BK1_IO1	-	-	-	-	EVEN TOUT
	PF10	-	-	-	-	-	-	-	-	-	QUADSPI_CLK	-	-	-	DCMI_D11	LCD_DE	EVEN TOUT
	PF11	-	-	-	-	-	SPI5_MOSI	-	-	-	-	SAI2_SDB	-	FMC_SDNRAS	DCMI_D12	-	EVEN TOUT



Table 12. STM32F765xx, STM32F767xx, STM32F768Ax and STM32F769xx alternate function mapping (continued)

Port		AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
		SYS	I2C4/UART5/TIM1/2	TIM3/4/5	TIM8/9/10/11/LPTIM1/DFSDM1/CEC	I2C1/2/3/4/USART1/CEC	SPI1/I2S1/SPI2/I2S2/SPI3/I2S3/SAI1/I2C4/UART4/DFSDM1	SPI2/I2S2/SPI3/I2S3/SAI1/I2C4/UART4/DFSDM1	SPI2/I2S2/SPI3/I2S3/SPI6/USART1/2/3/UART5/DFSDM1/SPDIF	SPI6/SAI2/USART6/UART4/5/7/8/OTG_FS/SPDIF	CAN1/2/TIM12/13/14/QUADSPI/FMC/LCD	SAI2/QUADSPI/SDMMC2/DFSDM1/OTG2_HS/OTG1_FS/LCD	I2C4/CAN3/SDMMC2/ETH	UART7/FMC/SDMMC1/MDIOS/OTG2_FS	DCMI/LCD/DSI	LCD	SYS
Port I	PI12	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_HS_YNC	EVEN TOUT
	PI13	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_VS_YNC	EVEN TOUT
	PI14	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_CLK	EVEN TOUT
	PI15	-	-	-	-	-	-	-	-	-	LCD_G2	-	-	-	-	LCD_R0	EVEN TOUT
Port J	PJ0	-	-	-	-	-	-	-	-	-	LCD_R7	-	-	-	-	LCD_R1	EVEN TOUT
	PJ1	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_R2	EVEN TOUT
	PJ2	-	-	-	-	-	-	-	-	-	-	-	-	-	DSI_TE	LCD_R3	EVEN TOUT
	PJ3	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_R4	EVEN TOUT
	PJ4	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_R5	EVEN TOUT
	PJ5	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_R6	EVEN TOUT
	PJ6	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_R7	EVEN TOUT
	PJ7	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_G0	EVEN TOUT
	PJ8	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_G1	EVEN TOUT
	PJ9	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_G2	EVEN TOUT
	PJ10	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_G3	EVEN TOUT

1. Guaranteed by design.
2. The reset temporization is measured from the power-on (POR reset or wakeup from V_{BAT}) to the instant when first instruction is read by the user application code.

5.3.6 Over-drive switching characteristics

When the over-drive mode switches from enabled to disabled or disabled to enabled, the system clock is stalled during the internal voltage set-up.

The over-drive switching characteristics are given in [Table 23](#). They are subject to general operating conditions for T_A .

Table 23. Over-drive switching characteristics⁽¹⁾

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Tod_swen	Over_drive switch enable time	HSI	-	45	-	μs
		HSE max for 4 MHz and min for 26 MHz	45	-	100	
		External HSE 50 MHz	-	40	-	
Tod_swdis	Over_drive switch disable time	HSI	-	20	-	
		HSE max for 4 MHz and min for 26 MHz.	20	-	80	
		External HSE 50 MHz	-	15	-	

1. Guaranteed by design.

5.3.7 Supply current characteristics

The current consumption is a function of several parameters and factors such as the operating voltage, ambient temperature, I/O pin loading, device software configuration, operating frequencies, I/O pin switching rate, program location in memory and executed binary code.

The current consumption is measured as described in [Figure 26: Current consumption measurement scheme](#).

All the run-mode current consumption measurements given in this section are performed with a reduced code that gives a consumption equivalent to CoreMark code.

1. Guaranteed by characterization results.
2. When analog peripheral blocks such as ADCs, DACs, HSE, LSE, HSI, or LSI are ON, an additional power consumption should be considered.
3. When the ADC is ON (ADON bit set in the ADC_CR2 register), add an additional power consumption of 1.73 mA per ADC for the analog part.

Table 33. Typical and maximum current consumption in Sleep mode, regulator ON

Symbol	Parameter	Conditions	f _{HCLK} (MHz)	Typ	Max ⁽¹⁾			Unit
					T _A = 25 °C	T _A = 85 °C	T _A = 105 °C	
I _{DD}	Supply current in Sleep mode	All peripherals enabled ⁽²⁾	216	128	144 ⁽³⁾	190 ⁽³⁾	-	mA
			200	119	134	180	214	
			180	105	118 ⁽³⁾	153 ⁽³⁾	178 ⁽³⁾	
			168	93	105	136	156	
			144	72	80	107	124	
			60	33	39	65	82	
			25	17	21	47	65	
		All peripherals disabled	216	18	25 ⁽³⁾	71 ⁽³⁾	-	
			200	17	24	70	112	
			180	14	20 ⁽³⁾	54 ⁽³⁾	75 ⁽³⁾	
			168	13	18	49	69	
			144	10	14	40	58	
			60	6	10	36	53	
			25	4	8	34	51	

1. Guaranteed by characterization results, unless otherwise specified.
2. When analog peripheral blocks such as ADCs, DACs, HSE, LSE, HSI, or LSI are ON, an additional power consumption should be considered.
3. Guaranteed by test in production.

Figure 36. MIPI D-PHY HS/LP clock lane transition timing diagram

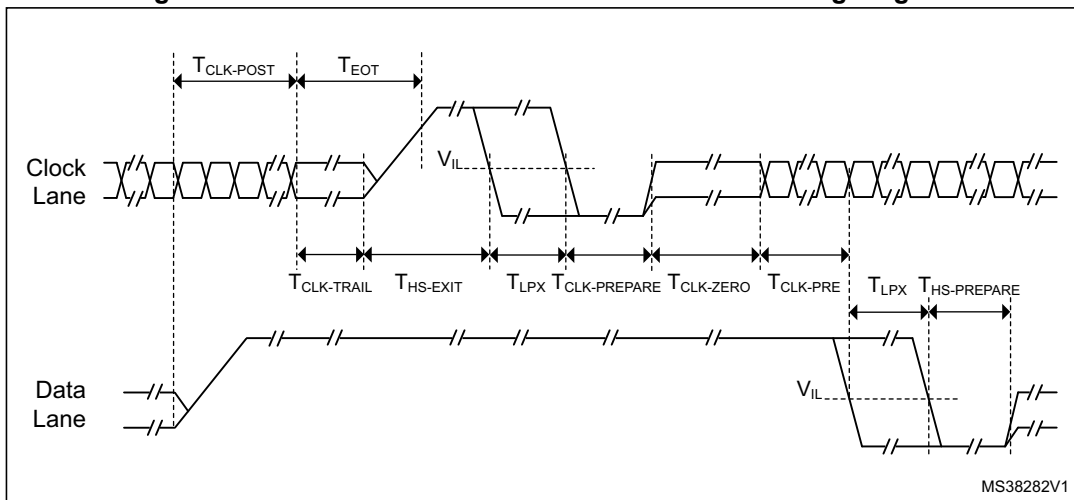
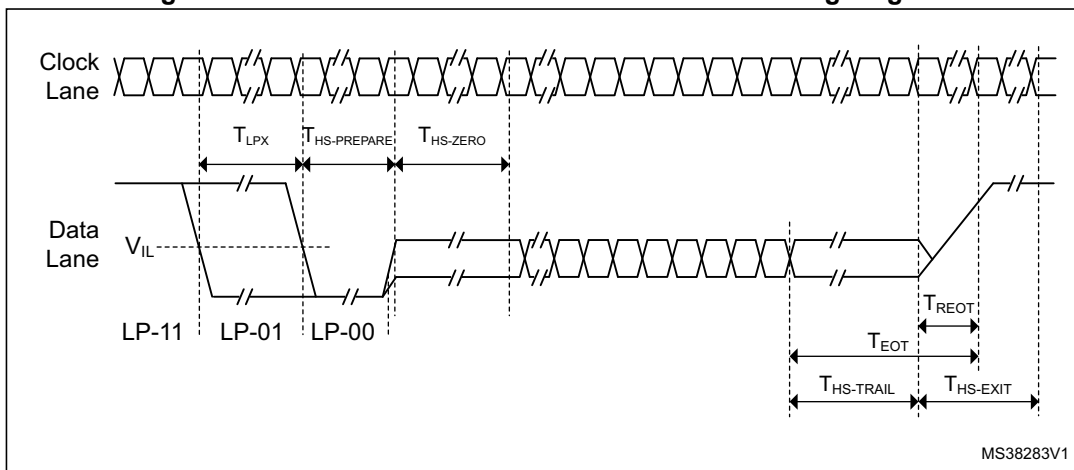


Figure 37. MIPI D-PHY HS/LP data lane transition timing diagram



5.3.14 MIPI D-PHY PLL characteristics

The parameters given in [Table 53](#) are derived from tests performed under temperature and V_{DD} supply voltage conditions summarized in [Table 17](#).

Table 53. DSI-PLL characteristics⁽¹⁾

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{PLL_IN}	PLL input clock	-	4	-	100	MHz
f_{PLL_INFIN}	PFD input clock	-	4	-	25	
f_{PLL_OUT}	PLL multiplier output clock	-	31.25	-	500	
f_{VCO_OUT}	PLL VCO output	-	500	-	1000	
t_{LOCK}	PLL lock time	-	-	-	200	μs

5.3.16 Memory characteristics

Flash memory

The characteristics are given at $T_A = -40$ to $105\text{ }^{\circ}\text{C}$ unless otherwise specified.

The devices are shipped to customers with the Flash memory erased.

Table 55. Flash memory characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{DD}	Supply current	Write / Erase 8-bit mode, $V_{DD} = 1.7\text{ V}$	-	14	-	mA
		Write / Erase 16-bit mode, $V_{DD} = 2.1\text{ V}$	-	17	-	
		Write / Erase 32-bit mode, $V_{DD} = 3.3\text{ V}$	-	24	-	

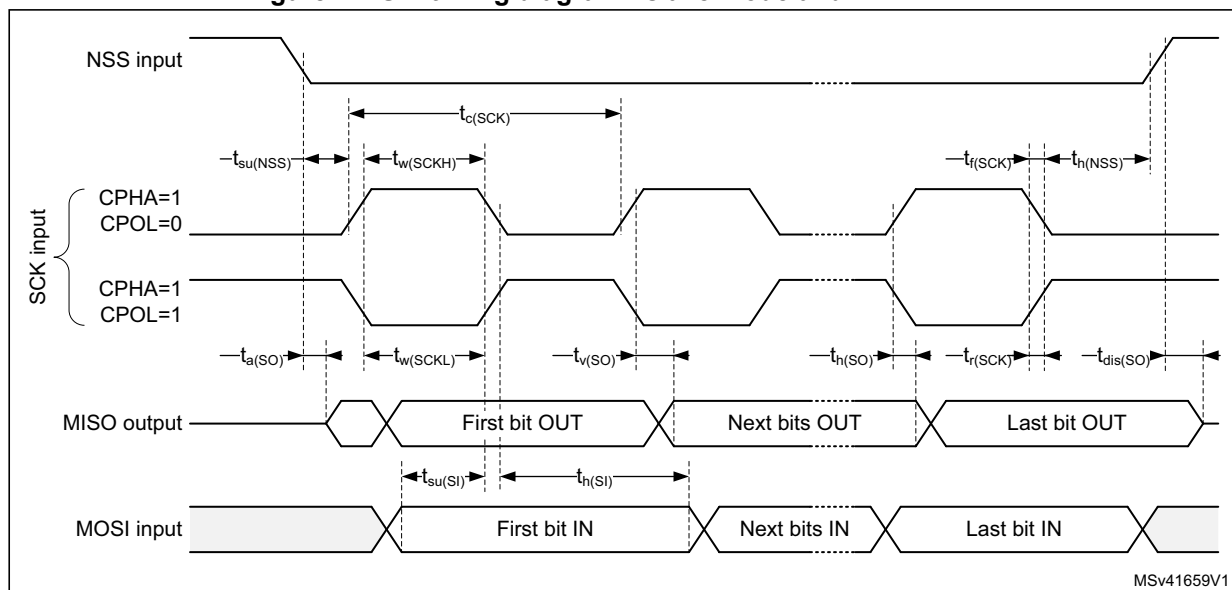
**Table 56. Flash memory programming (single bank configuration
nDBANK=1)**

Symbol	Parameter	Conditions	Min ⁽¹⁾	Typ	Max ⁽¹⁾	Unit
t_{prog}	Word programming time	Program/erase parallelism (PSIZE) = x 8/16/32	-	16	100 ⁽²⁾	μs
$t_{ERASE32KB}$	Sector (32 KB) erase time	Program/erase parallelism (PSIZE) = x 8	-	400	800	ms
		Program/erase parallelism (PSIZE) = x 16	-	250	600	
		Program/erase parallelism (PSIZE) = x 32	-	200	500	
$t_{ERASE128KB}$	Sector (128 KB) erase time	Program/erase parallelism (PSIZE) = x 8	-	1100	2400	ms
		Program/erase parallelism (PSIZE) = x 16	-	800	1400	
		Program/erase parallelism (PSIZE) = x 32	-	500	1100	
$t_{ERASE256KB}$	Sector (256 KB) erase time	Program/erase parallelism (PSIZE) = x 8	-	2.1	4	s
		Program/erase parallelism (PSIZE) = x 16	-	1.5	2.6	
		Program/erase parallelism (PSIZE) = x 32	-	1	2	
t_{ME}	Mass erase time	Program/erase parallelism (PSIZE) = x 8	-	16	32	s
		Program/erase parallelism (PSIZE) = x 16	-	11	22	
		Program/erase parallelism (PSIZE) = x 32	-	8	16	

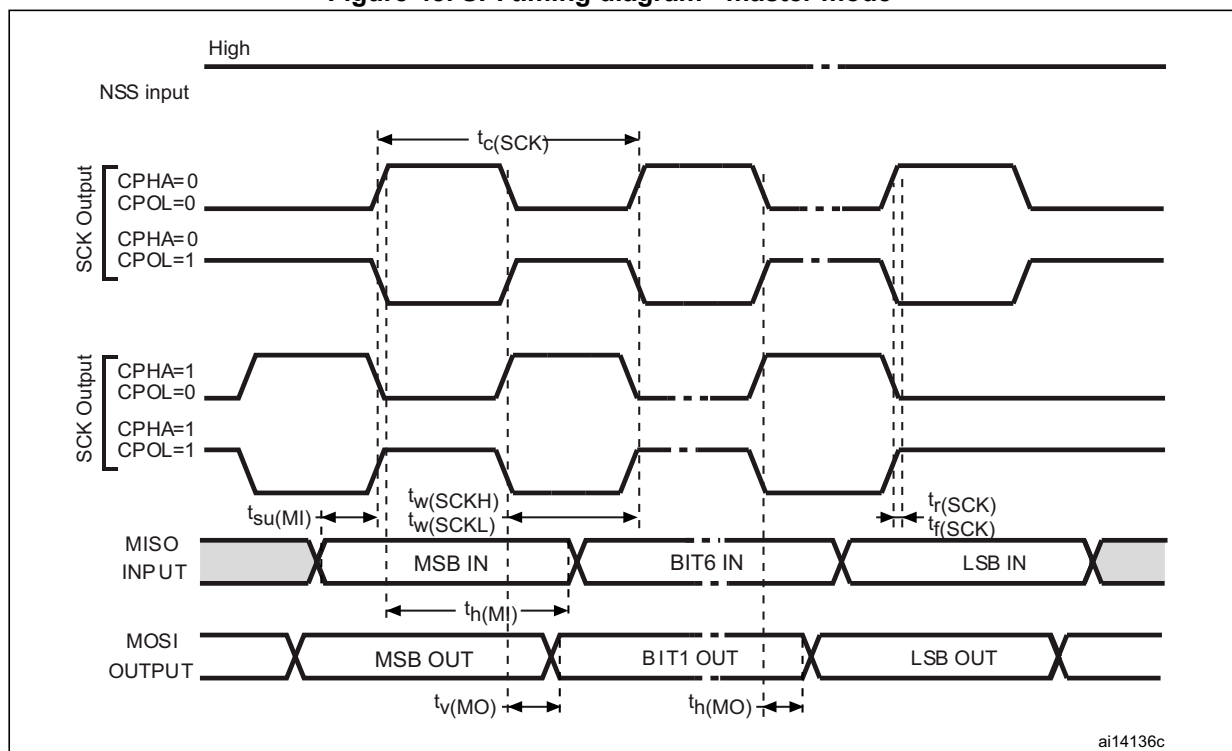
Table 82. DAC characteristics (continued)

Symbol	Parameter	Min	Typ	Max	Unit	Comments
$I_{DDA}^{(4)}$	DAC DC V_{DDA} current consumption in quiescent mode ⁽³⁾	-	280	380	μA	With no load, middle code (0x800) on the inputs
		-	475	625	μA	With no load, worst code (0xF1C) at $V_{REF+} = 3.6 V$ in terms of DC consumption on the inputs
DNL ⁽⁴⁾	Differential non linearity Difference between two consecutive code-1LSB)	-	-	± 0.5	LSB	Given for the DAC in 10-bit configuration.
		-	-	± 2	LSB	Given for the DAC in 12-bit configuration.
INL ⁽⁴⁾	Integral non linearity (difference between measured value at Code i and the value at Code i on a line drawn between Code 0 and last Code 1023)	-	-	± 1	LSB	Given for the DAC in 10-bit configuration.
		-	-	± 4	LSB	Given for the DAC in 12-bit configuration.
Offset ⁽⁴⁾	Offset error (difference between measured value at Code (0x800) and the ideal value = $V_{REF+}/2$)	-	-	± 10	mV	Given for the DAC in 12-bit configuration
		-	-	± 3	LSB	Given for the DAC in 10-bit at $V_{REF+} = 3.6 V$
		-	-	± 12	LSB	Given for the DAC in 12-bit at $V_{REF+} = 3.6 V$
Gain error ⁽⁴⁾	Gain error	-	-	± 0.5	%	Given for the DAC in 12-bit configuration
$t_{SETTLING}^{(4)}$	Settling time (full scale: for a 10-bit input code transition between the lowest and the highest input codes when DAC_OUT reaches final value $\pm 4LSB$)	-	3	6	μs	$C_{LOAD} \leq 50 pF$, $R_{LOAD} \geq 5 k\Omega$
THD ⁽⁴⁾	Total Harmonic Distortion Buffer ON	-	-	-	dB	$C_{LOAD} \leq 50 pF$, $R_{LOAD} \geq 5 k\Omega$
Update rate ⁽²⁾	Max frequency for a correct DAC_OUT change when small variation in the input code (from code i to i+1LSB)	-	-	1	MS/s	$C_{LOAD} \leq 50 pF$, $R_{LOAD} \geq 5 k\Omega$
$t_{WAKEUP}^{(4)}$	Wakeup time from off state (Setting the ENx bit in the DAC Control register)	-	6.5	10	μs	$C_{LOAD} \leq 50 pF$, $R_{LOAD} \geq 5 k\Omega$ input code between lowest and highest possible ones.
PSRR+ ⁽²⁾	Power supply rejection ratio (to V_{DDA}) (static DC measurement)	-	-67	-40	dB	No R_{LOAD} , $C_{LOAD} = 50 pF$

- V_{DDA} minimum value of 1.7 V is obtained with the use of an external power supply supervisor (refer to [Section 2.18.2: Internal reset OFF](#)).
- Guaranteed by design.
- The quiescent mode corresponds to a state where the DAC maintains a stable output level to ensure that no dynamic consumption occurs.
- Guaranteed by characterization results.

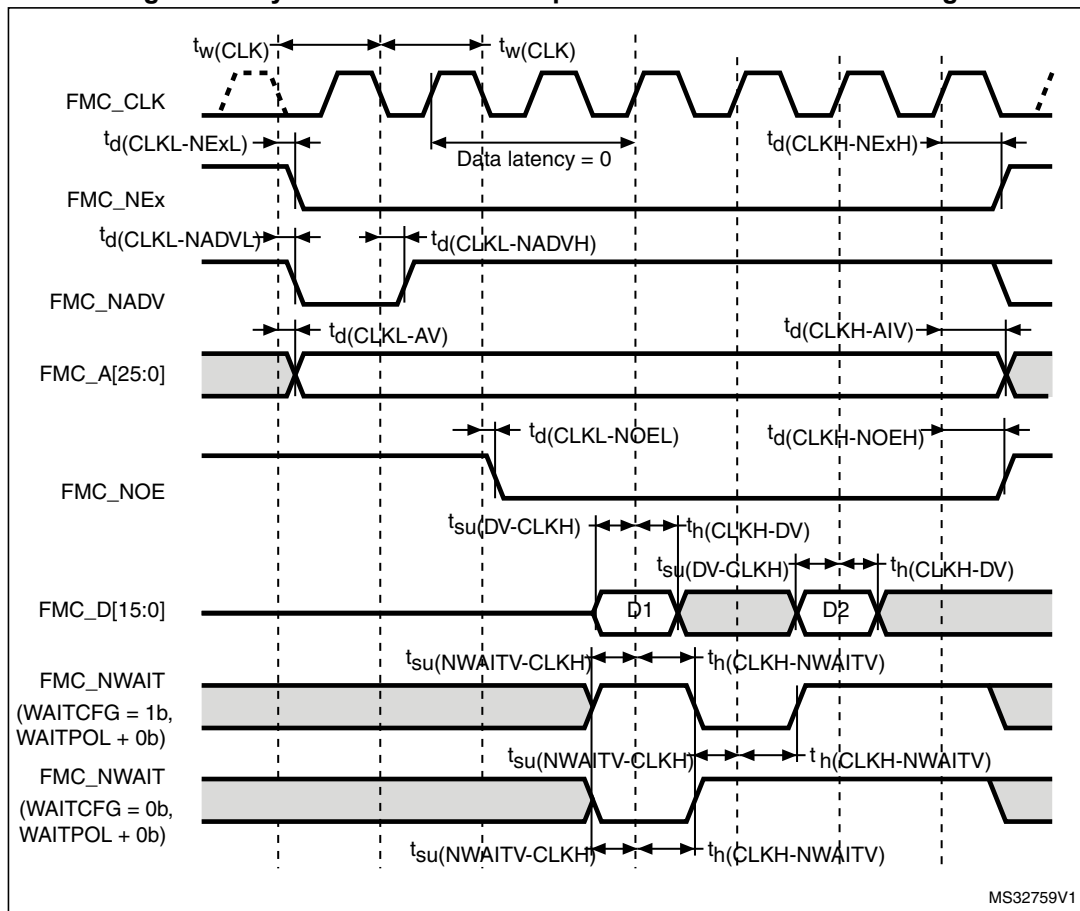
Figure 47. SPI timing diagram - slave mode and CPHA = 1⁽¹⁾

1. Measurement points are done at $0.5V_{DD}$ and with external $C_L = 30$ pF.

Figure 48. SPI timing diagram - master mode⁽¹⁾

1. Measurement points are done at $0.5V_{DD}$ and with external $C_L = 30$ pF.

Figure 67. Synchronous non-multiplexed NOR/PSRAM read timings

Table 110. Synchronous non-multiplexed NOR/PSRAM read timings⁽¹⁾

Symbol	Parameter	Min	Max	Unit
$t_w(\text{CLK})$	FMC_CLK period	$2T_{\text{HCLK}} - 0.5$	-	ns
$t_{\text{d}}(\text{CLKL-NExL})$	FMC_CLK low to FMC_NEx low ($x=0..2$)	-	2	
$t_{\text{d}}(\text{CLKH-NExH})$	FMC_CLK high to FMC_NEx high ($x=0..2$)	$T_{\text{HCLK}} + 0.5$	-	
$t_{\text{d}}(\text{CLKL-NADV})$	FMC_CLK low to FMC_NADV low	-	0.5	
$t_{\text{d}}(\text{CLKL-NADVH})$	FMC_CLK low to FMC_NADV high	0	-	
$t_{\text{d}}(\text{CLKL-AV})$	FMC_CLK low to FMC_Ax valid ($x=16..25$)	-	2.5	
$t_{\text{d}}(\text{CLKH-AIV})$	FMC_CLK high to FMC_Ax invalid ($x=16..25$)	T_{HCLK}	-	
$t_{\text{d}}(\text{CLKL-NOEL})$	FMC_CLK low to FMC_NOE low	-	1.5	
$t_{\text{d}}(\text{CLKH-NOEH})$	FMC_CLK high to FMC_NOE high	$T_{\text{HCLK}} + 0.5$	-	
$t_{\text{su}}(\text{DV-CLKH})$	FMC_D[15:0] valid data before FMC_CLK high	1.5	-	
$t_{\text{h}}(\text{CLKH-DV})$	FMC_D[15:0] valid data after FMC_CLK high	3.5	-	
$t_{\text{su}}(\text{NWAITV-CLKH})$	FMC_NWAIT valid before FMC_CLK high	2	-	
$t_{\text{h}}(\text{CLKH-NWAITV})$	FMC_NWAIT valid after FMC_CLK high	3.5	-	

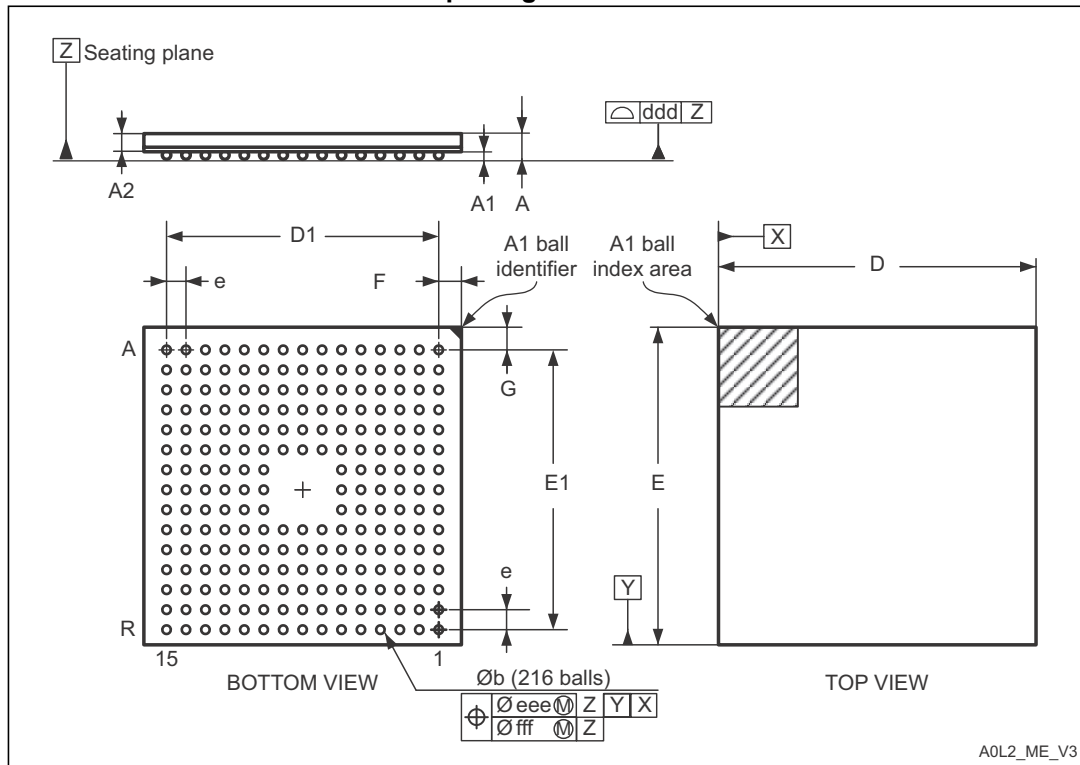
Table 128. LQFP208, 28 x 28 mm, 208-pin low-profile quad flat package mechanical data

Symbol	millimeters			inches ⁽¹⁾		
	Min	Typ	Max	Min	Typ	Max
A	-	-	1.600	--	-	0.0630
A1	0.050	-	0.150	0.0020	-	0.0059
A2	1.350	1.400	1.450	0.0531	0.0551	0.0571
b	0.170	0.220	0.270	0.0067	0.0087	0.0106
c	0.090	-	0.200	0.0035	-	0.0079
D	29.800	30.000	30.200	1.1732	1.1811	1.1890
D1	27.800	28.000	28.200	1.0945	1.1024	1.1102
D3	-	25.500	-	-	1.0039	-
E	29.800	30.000	30.200	1.1732	1.1811	1.1890
E1	27.800	28.000	28.200	1.0945	1.1024	1.1102
E3	-	25.500	-	-	1.0039	-
e	-	0.500	-	-	0.0197	-
L	0.450	0.600	0.750	0.0177	0.0236	0.0295
L1	-	1.000	-	-	0.0394	-
k	0°	3.5°	7.0°	0°	3.5°	7.0°
ccc	-	-	0.080	-	-	0.0031

1. Values in inches are converted from mm and rounded to 4 decimal digits.

6.7 TFBGA216, 13 x 13 x 0.8 mm thin fine-pitch ball grid array package information

Figure 101. TFBGA216, 13 × 13 × 0.8 mm thin fine-pitch ball grid array package outline



1. Drawing is not to scale.

Table 133. TFBGA216, 13 × 13 × 0.8 mm thin fine-pitch ball grid array package mechanical data

Symbol	millimeters			inches ⁽¹⁾		
	Min	Typ	Max	Min	Typ	Max
A	-	-	1.100	-	-	0.0433
A1	0.150	-	-	0.0059	-	-
A2	-	0.760	-	-	0.0299	-
b	0.350	0.400	0.450	0.0138	0.0157	0.0177
D	12.850	13.000	13.150	0.5118	0.5118	0.5177
D1	-	11.200	-	-	0.4409	-
E	12.850	13.000	13.150	0.5118	0.5118	0.5177
E1	-	11.200	-	-	0.4409	-
e	-	0.800	-	-	0.0315	-
F	-	0.900	-	-	0.0354	-

Table 133. TFBGA216, 13 × 13 × 0.8 mm thin fine-pitch ball grid array package mechanical data (continued)

Symbol	millimeters			inches ⁽¹⁾		
	Min	Typ	Max	Min	Typ	Max
G	-	0.900	-	-	0.0354	-
ddd	-	-	0.100	-	-	0.0039
eee	-	-	0.150	-	-	0.0059
fff	-	-	0.080	-	-	0.0031

1. Values in inches are converted from mm and rounded to 4 decimal digits.

Figure 102. TFBGA216, 13 x 13 mm, 0.8 mm pitch, thin fine-pitch ball grid array package recommended footprint

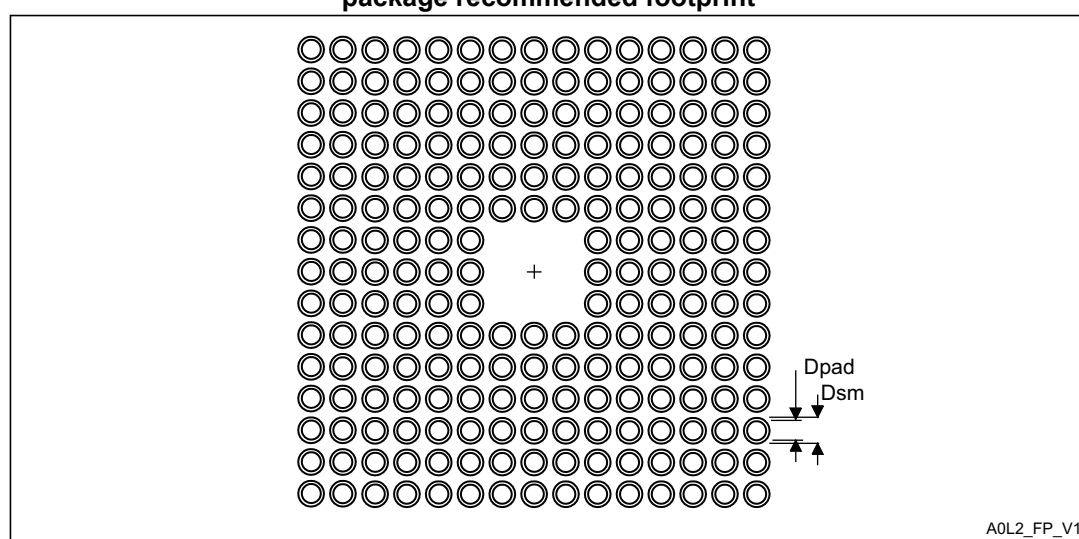


Table 134. TFBGA216 recommended PCB design rules (0.8 mm pitch BGA)

Dimension	Recommended values
Pitch	0.8
Dpad	0.400 mm
Dsm	0.470 mm typ. (depends on the soldermask registration tolerance)
Stencil opening	0.400 mm
Stencil thickness	Between 0.100 mm and 0.125 mm
Pad trace width	0.120 mm